EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L10	1	257/789.ccls. and diameter with (nm (nano near2 meter)) and (filler particle) with density	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/12 00:15
L11	0	257/789.ccls. and diameter with (nm (nano near2 meter)) with density	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/12 00:15
L12	6	257/789.ccls. and diameter with (nm (nano near2 meter)) and density	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/12 00:16
L13	8	257/789.ccls. and diameter with (nm (nano near2 meter)) and density	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:16
L15	13	257/789.ccls. and (mold\$3 encapsulant encapsulat\$3 sealant seal\$3) with (nanometer nm (nano near2 meter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:23
L16	14	257/787.ccls. and (mold\$3 encapsulant encapsulat\$3 sealant seal\$3) with (nanometer nm (nano near2 meter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:25
L17	2	257/790.ccls. and (mold\$3 encapsulant encapsulat\$3 sealant seal\$3) with (nanometer nm (nano near2 meter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:27
L18	3	257/794.ccls. and (mold\$3 encapsulant encapsulat\$3 sealant seal\$3) with (nanometer nm (nano near2 meter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:27
L19	1	257/795.ccls. and (mold\$3 encapsulant encapsulat\$3 sealant seal\$3) with (nanometer nm (nano near2 meter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:28

L20	538	(mold\$3 encapsulant encapsulat\$3 sealant seal \$3) with (nanometer nm (nano near2 meter)) same density	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:28
L21	356	20 and @ad<="20030331"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:28
L22	60	21 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:29
L23	175	Usui-Ryosuke.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:32
L24	161	Mizuhara-Hideki.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:36
L26	3014	Nakamura-Takeshi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:41
L29	286	26 and (mold\$3 encapsulant encapsulat\$3 sealant seal \$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:42
L30	13	29 and (nm (nano near2 meter))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:42
L31	42	257/E31.117	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:44
L32	9	257/E31.118	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:45

L34	110	257/E51.02	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:45
L35	81	257/E23.116	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:45
L36	15	257/E23.121	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:46
L37	37	257/E23.128	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/12 00:46

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